

IN THE CLAIMS:

Please amend the claims as follows:

1-9. (Cancelled)

10. (Currently Amended) A method for producing a printed wiring board made by forming a conductor wiring by printing an electrically conductive paste containing metal particles M used as an electrically conductive filler and a binder B in volume ratio of M/B 1/1 to 1.9/1 on the surface of the board for printed wiring, made by comprising the steps of:

treating a [[the]] surface of a board made of at least one resin selected from among the group consisting of polyimide, polyethylene naphthalate, polyamide-imide, polyethylene terephthalate, wholly aromatic polyamide, liquid crystalline polyester, and fluorine resin wherein the conductor wiring is to be formed for forming a conductor wiring thereon by one of the following surface treatment methods, [[:]]

(1) surface roughening treatment for achieving center line average roughness Ra in a range from 30 to 300 nm, [[:]]

(2) plasma treatment, [[:]]

(3) surface roughening treatment for achieving center line average roughness Ra in a range from 30 to 300 nm followed by plasma treatment, or

(4) surface roughening treatment for achieving center line average roughness Ra in a range from 30 to 300 nm followed by the step of forming a porous metal layer made of at least one kind of metal selected from among the group consisting of Al, Cr, Co, Ni, Cu and Ag, by sputtering; [[:]]

forming a conductor wiring by printing an electrically conductive paste containing metal particles M used as an electrically conductive filler and a binder B in volume ratio of M/B=1/1 to 1.9/1 on the surface of the board for the printed wiring; [[;]] and

forming etching the surface of the conductor wiring on at least a portion thereof used for connection with an external circuit so as to expose the metal particles on the surface, and forming a plating layer by electroless plating on the surface of the conductor wiring where the metal particles have been exposed by etching the surface of the conductor wiring on at least a portion thereof used for connection with an external circuit so as to expose the metal particles on the surface.

11-12. (Cancelled)